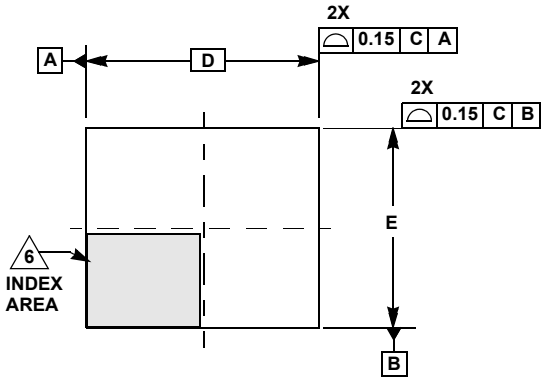
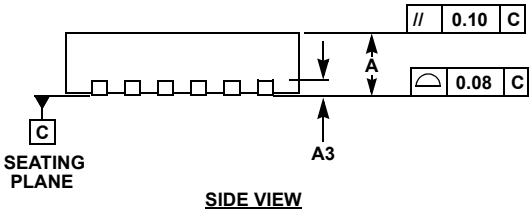
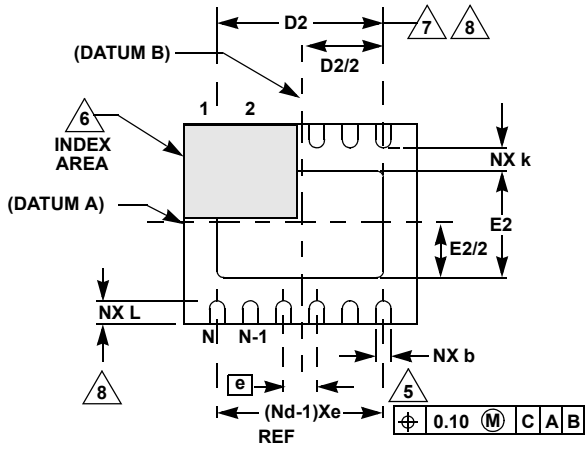
Thin Dual Flat No-Lead Plastic Package (TDFN)



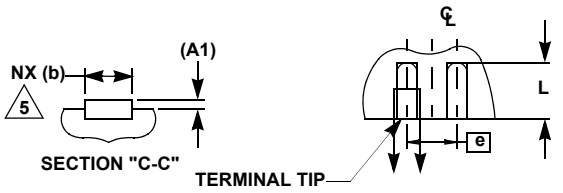
TOP VIEW



SIDE VIEW



BOTTOM VIEW



FOR EVEN TERMINAL/SIDE

L12.4x3A

12 LEAD THIN DUAL FLAT NO-LEAD PLASTIC PACKAGE (COMPLIANT TO JEDEC MO-229-WGED-4 ISSUE C)

SYMBOL	MILLIMETERS			NOTES
	MIN	NOMINAL	MAX	
A	0.70	0.75	0.80	-
A1	-	-	0.05	-
A3		0.20 REF		-
b	0.18	0.23	0.30	5,8
D		4.00 BSC		-
D2	3.15	3.30	3.40	7,8
E		3.00 BSC		-
E2	1.55	1.70	1.80	7,8
e		0.50 BSC		-
k	0.20	-	-	-
L	0.30	0.40	0.50	8
N		12		2
Nd		6		3

Rev. 1 10/15

NOTES:

1. Dimensioning and tolerancing conform to ASME Y14.5-1994.
2. N is the number of terminals.
3. Nd refers to the number of terminals on D.
4. All dimensions are in millimeters. Angles are in degrees.
5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
7. Dimensions D2 and E2 are for the exposed pads which provide improved electrical and thermal performance.
8. Nominal dimensions are provided to assist with PCB Land Pattern Design efforts, see Intersil Technical Brief TB389.
9. Tiebar shown (if present) is a non-functional feature and maybe located on any of the 4 sides (or ends).